



Save Time

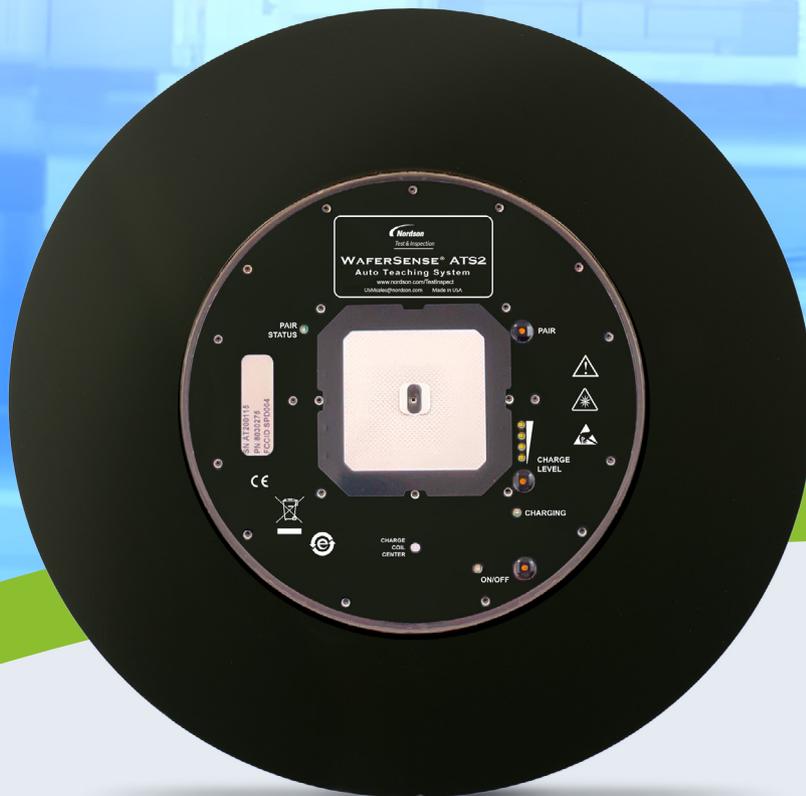


Save Expense



Improve Yields

Semiconductor fabs and OEMs worldwide value the accuracy, precision and versatility of the WaferSense ATS2 – The most efficient and effective wireless measurement device for wafer handoff teaching.



WaferSense[®]

Auto Teaching System™ (ATS2)

Metrology Sensors

Speed achieving accurate wafer hand-off calibration, proper alignment and set-ups.

“Sees” inside semiconductor equipment to capture three dimensional offset data (x, y and z) to quickly teach wafer transfer positions with accuracy to 100µm.

Improve Yields

Improve yields and lower particulate contamination with accurate wafer handoff calibration.

- Capture offset data for accurate calibration of transfer positions as the wafer-like ATS2 moves through your semi-conductor equipment.
- Improve the yield of your manufacturing process with calibrated equipment.

Repeatable & Reproducible

Achieve repeatable and reproducible semiconductor equipment setups.

- Eliminate technician-to-technician variation with the ATS2 calibration process enabling repeatable and reproducible setup and maintenance checks.

Reduce Equipment Downtime

Equipment Downtime from hours to minutes.

- Save time troubleshooting with the wireless and vacuum compatible ATS2, as equipment stays sealed during inspection.
- Increase equipment availability and reduce manpower and consumable expense.

Speed Trouble-shooting

Speed trouble-shooting and lower consumable expense with visual inspection.

- Receive real-time images as robots move the ATS2 through the tool. Nordson Spectrum™ software graphical user interface provides x, y and z offsets that eliminate guesswork.
- Search for lost wafers, verify that pedestals are free of debris without opening the tool.

For more information, speak with your Nordson representative or contact your Nordson regional office

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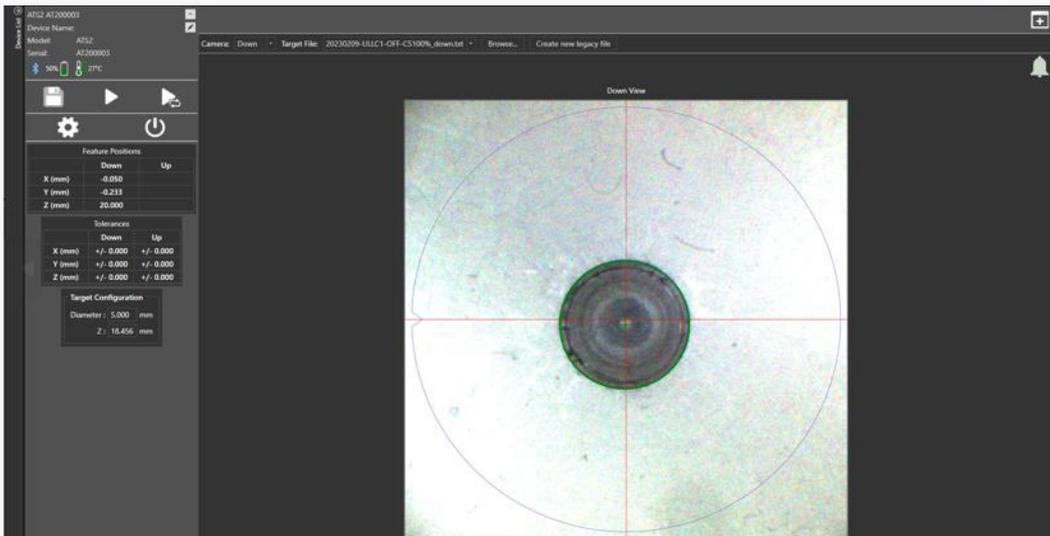
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Specifications

Form Factor	Available in 200mm and 300mm
Part Numbers	200 mm (8030276), 300 mm (8030275), 300 mm with Quartz Ring (8030423)
Two on-board cameras	Reports x-y-z offset from the teaching wafer to a target inside the equipment so you can teach wafer transfer coordinates. Cameras: 1 upward, 1 downward. Color images with white light illumination.
Software	Nordson Spectrum
Durable housing	Chemically hardened glass (CHG)
Weight	165 grams ± 25 grams (200 mm), 225 grams ± 25 grams (300 mm)
Sensor edge and body thickness	Edge: 0.80 mm; Body: 3.5 mm (300mm)
Operating pressure	<10 ⁻⁶ to 760 torr
Operating temperature	20 to 60 °C
Communication	Bluetooth, WiFi
Operating system	Windows 11
Product components	Teaching device, charging clean case, carrying suitcase, accessory communication gateway
Calibration	Factory recalibration recommended annually
Battery-duration	~1.8 hrs with 2 cameras on at 10% illumination / ~2.3 hrs at idle
Working distance	6.5 mm to 45 mm
Nominal working distance	10 mm (downward), 12mm (upward)
Measurement Repeatability	0.025 mm for X and Y position at nominal focus distance ¹
Accuracy	0.05 mm for X and Y position at nominal focus distance ²



Nordson Spectrum Software

Displays real-time video and measurements of target features, logs offsets and user comments. Allows teaching of circular, square and crossed features. Review functionality integrated; replays log file data for review and analysis.

